

06-04-1998

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1. Name of conveying party(ies):

YUNG-KUAN HSIAO, CHENG-MING WU AND
YU-HUA LEEAdditional name(s) or conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance



Assignment



Merger



Security Agreement



Change of Name



other _____

Execution Date: 4/10/98

2. Name and address of receiving party(ies):

Name: Taiwan Semiconductor Manufacturing Company

Internal Address:

Street Address:

121 Park Ave. 3
Science-Based Industrial Park
City: Hsin-Chu Zip:
Country: Taiwan, R.O.C.Additional name(s) & address(es) attached? Yes ☐ No ☒

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 4/10/98A. Patent Application No(s)B. Patent No.(s)Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: GEORGE O. SAILE

Internal Address: _____

Street Address: 20 MCINTOSH DRIVECity: POUGHKEEPSIE State: NY ZIP: 126036. Total no. of applications and patents involved: 17. Total fee (37 CFR 3.41): \$ 40.00

Enclosed



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STEPHEN B. ACKERMAN

Name of Person Signing

Signature

5/6/98

Date

Total number of pages comprising cover sheet: 3

PATENT

REEL: 9202 FRAME: 0567

MRD 5/11/98

JCS18 U.S. PTO
09/075368
05/11/98

For ☒ U.S. and/or ☒ Foreign Rights

For ☒ Application or ☐ U.S. Patent

By ☒ Inventor(s) or ☐ Present Owner

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR:

YUNG-KUAN HSIAO
Type or print name of ASSIGNOR

7F No. 99, Lane 376 Sec. 1
Address

Kuang-Fu Rd., Hsinchu Taiwan

Republic of China
Nationality

CHENG-MING WU
Type or print name of ASSIGNOR

No 23, Alley 130, Chyh-Kaan East Rd.,
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Tzekuan, Kao Hsiung, Taiwan

Republic of China
Nationality

YU-HUA LEE
Type or print name of ASSIGNOR

8F-1, No. 66, Ming-De Rd.,
Address

Chutung, Hsinchu, Taiwan

Republic of China
Nationality

ASSIGNEE:

Taiwan Semiconductor Manufacturing Co. Ltd.

121 Park Ave. 3

Science-Based Industrial Park

Hsin-Chu, Taiwan, R.O.C.

Taiwan, R.O.C.

Nationality

and the successors, assigns and legal representatives of the ASSIGNEE

(complete one of the following)

☒ the entire right, title and interest

☐ an undivided _____ percent (____%) interest for the United States and its territorial possessions
(check the following box if foreign rights are also to be assigned)

☒ and in all foreign countries

in and to any and all improvements which are disclosed in the invention entitled:

A Method For Reducing Bonding Pad Loss Using A Capping Layer When Etching Bonding Pad Passivation Openings

PATENT

REEL: 9202 FRAME: 0568

and which is found in

- (a) ☒ U.S. patent application executed on even date herewith
(b) ☐ U.S. patent application executed on _____
(c) ☐ U.S. application serial no. _____ filed on _____
(d) ☐ U.S. patent no. _____ issued _____
(e) ☐ and any legal equivalent thereof in a foreign country, including the right to claim priority
(also check (e) if foreign application(s) is also being assigned)

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute, thereof, and as to letters patent any re-issue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof

IN WITNESS WHEREOF, I / We have signed this

Apr. 10 1998 (Date of signing)

WARNING Date of signing must be the same as the date of execution of the application if item (a) was checked above.

Yang Kuan Hsing
Signature of ASSIGNOR(S)
James H. Lee
Chun Hua, Lee

If ASSIGNOR is a legal entity complete the following information

Type or print the name of the above person authorized to sign on behalf of ASSIGNOR

Title

Note: No witnessing, notarization or legalization is necessary, if the assignment is notarized or legalized then it will only be prima facie evidence (35 USC 261). Use next page if notarization is desired.

Notarization or Legalization Page Added.

RECORDED: 05/11/1998

PATENT
REEL: 9202 FRAME: 0569